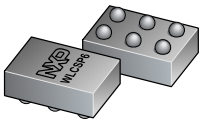

SOT1379-4

WLCSP6, wafer level chip scale package, 6 terminals, 0.22 mm pitch, 0.66 mm x 0.45 mm x 0.28 mm body

23 June 2020 Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	WLCSP6
Package style descriptive code	WLCSP (wafer level chip-size package)
Mounting method type	S (surface mount)
Issue date	24-06-2019
Manufacturer package code	98ASA01480D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	0.6425	0.66	0.6775	mm
package width	0.4325	0.45	0.4675	mm
seated height	-	0.28	0.305	mm
nominal pitch	-	0.22	-	mm
actual quantity of termination	-	6	-	

2 Package outline

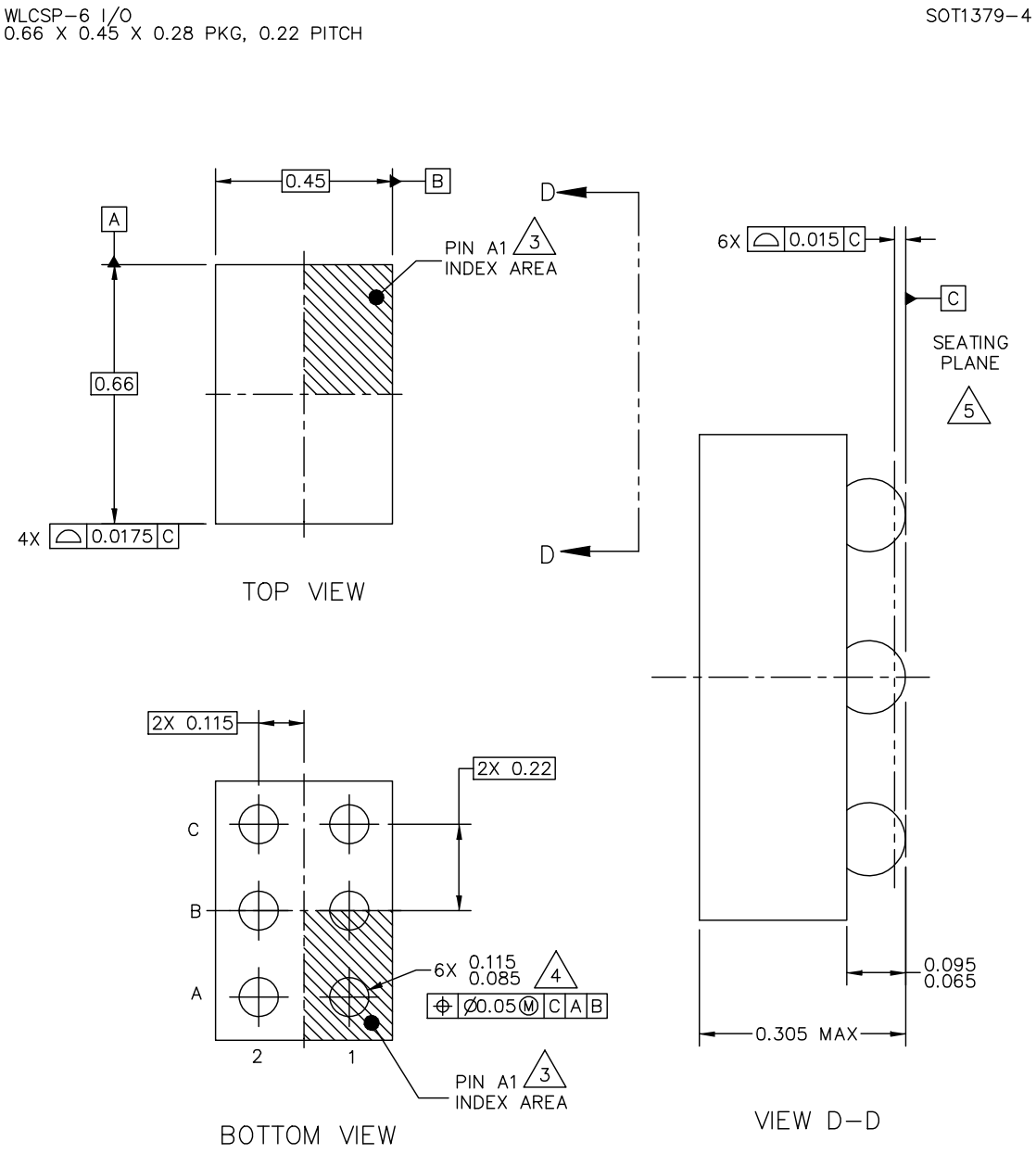

Figure 1. Package outline WLCSP6 (SOT1379-4)

3 Soldering

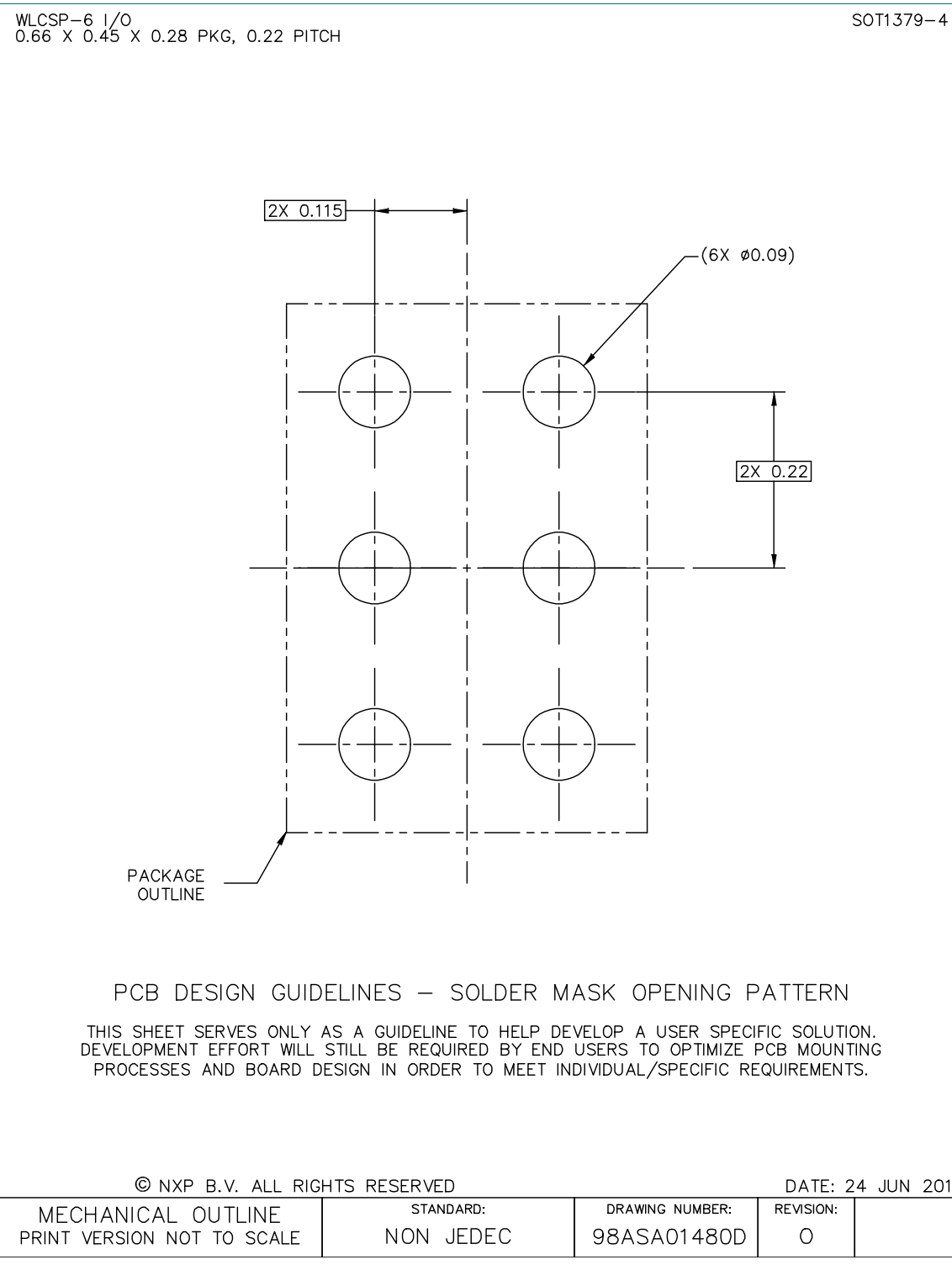

Figure 2. Reflow soldering footprint part1 for WLCSP6 (SOT1379-4)

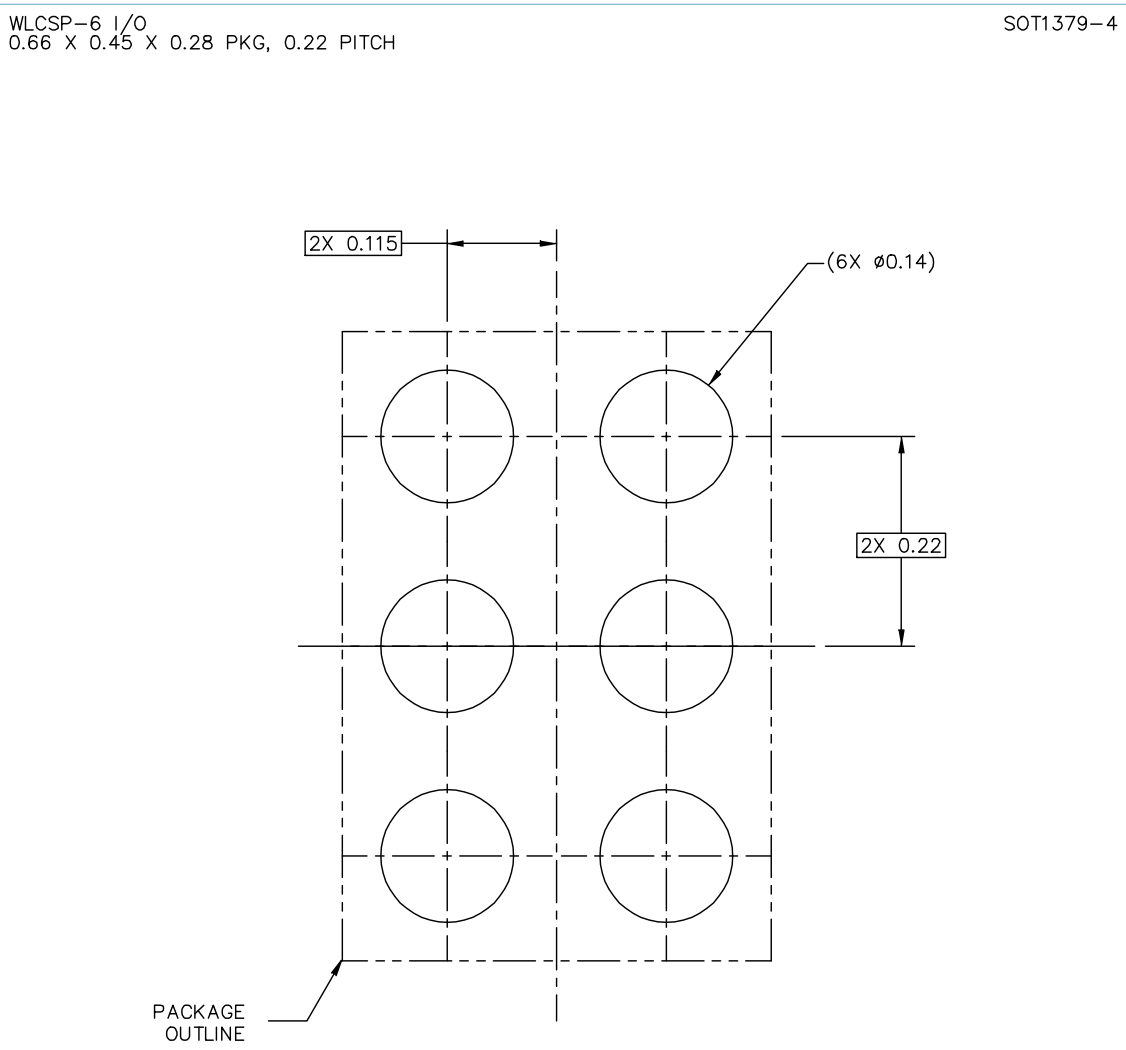

Figure 3. Reflow soldering footprint part2 for WLCSP6 (SOT1379-4)

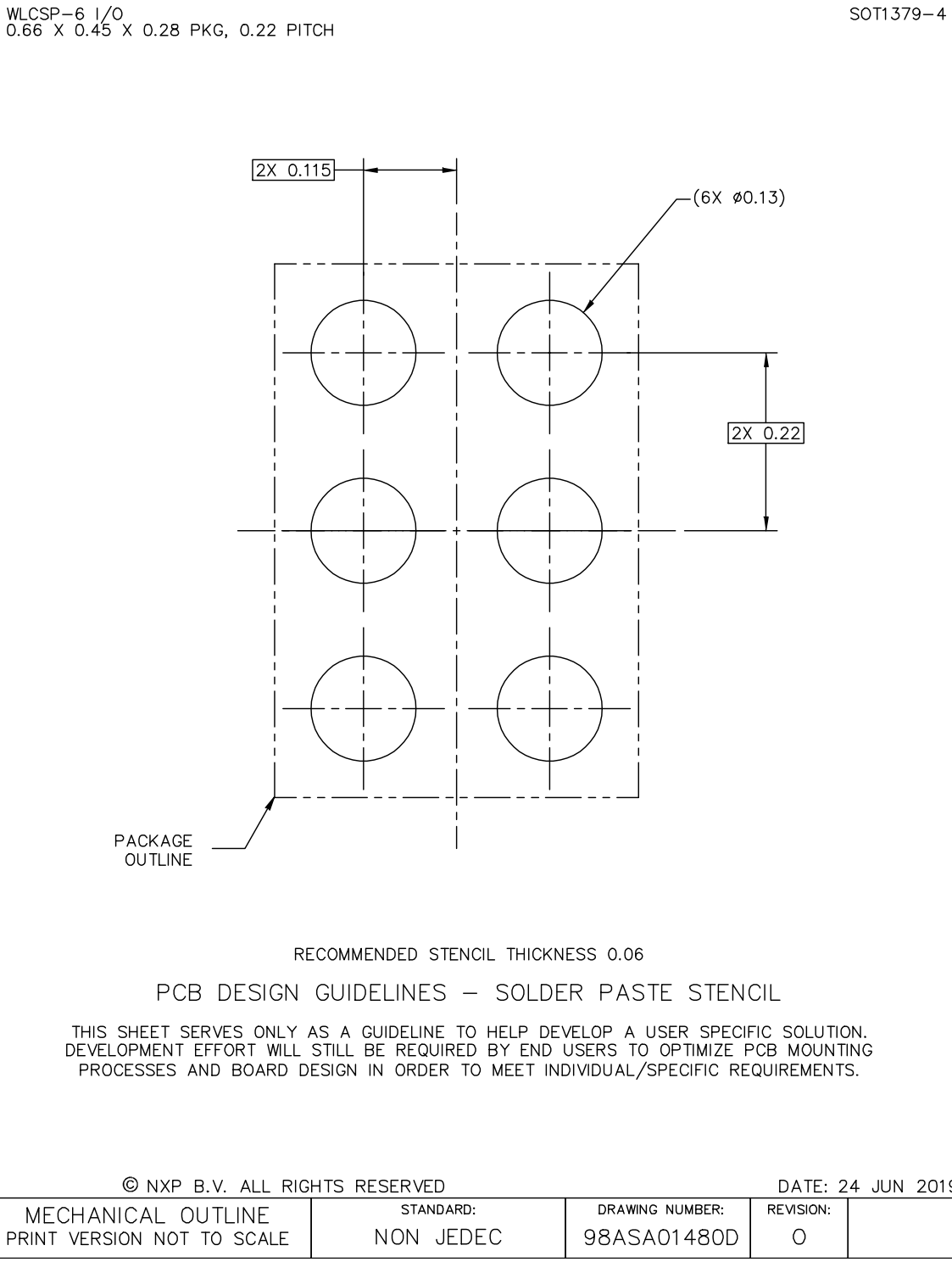

Figure 4. Reflow soldering footprint part3 for WLCSP6 (SOT1379-4)

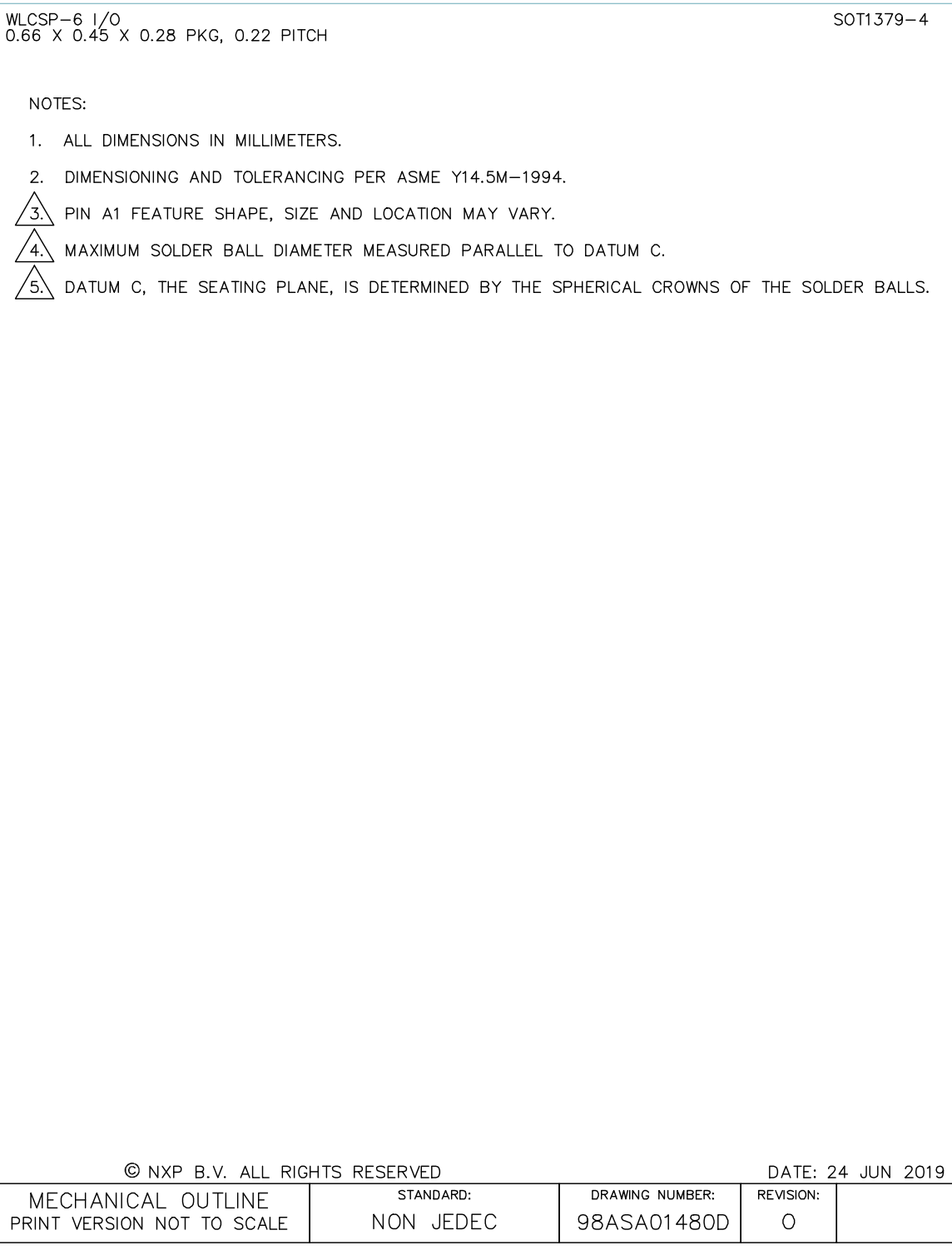

Figure 5. Package outline note of WLCSP6 (SOT1379-4)

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SOT1379-4

WLCSP6, wafer level chip scale package, 6 terminals, 0.22 mm pitch, 0.66 mm x 0.45 mm x 0.28 mm body

Contents

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